

Dual N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
30	0.022 at $V_{GS} = 10$ V	7.5
	0.030 at $V_{GS} = 4.5$ V	6.5

FEATURES

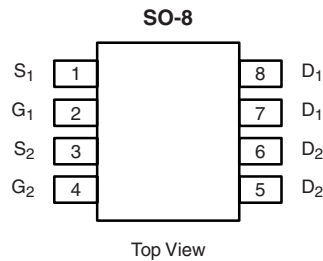
- TrenchFET[®] Power MOSFET
- PWM Optimized
- 100 % R_g Tested



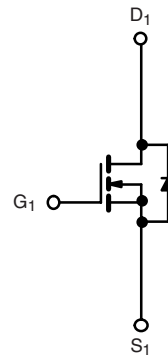
RoHS
COMPLIANT

APPLICATIONS

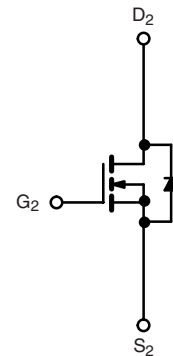
- Symmetrical Buck-Boost DC/DC Converter



Ordering Information: Si4804BDY-T1-E3 (Lead (Pb)-free)



N-Channel MOSFET



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted					
Parameter	Symbol	10 sec	Steady State	Unit	
Drain-Source Voltage	V_{DS}	30		V	
Gate-Source Voltage	V_{GS}	± 20			
Continuous Drain Current ($T_J = 150$ °C) ^a	I_D	$T_A = 25$ °C	7.5	5.7	A
		$T_A = 70$ °C	6.0	4.6	
Pulsed Drain Current	I_{DM}	30			
Continuous Source Current (Diode Conduction) ^a	I_S	1.7	0.9		
Maximum Power Dissipation ^a	P_D	$T_A = 25$ °C	2.0	1.1	W
		$T_A = 70$ °C	1.3	0.7	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limits		Unit	
		Typ	Max		
Maximum Junction-to-Ambient ^a	R_{thJA}	$t \leq 10$ sec	52	62.5	°C/W
		Steady State	93	110	
Maximum Junction-to-Foot (Drain)	R_{thJF}	Steady State	35	40	

Notes:

a. Surface Mounted on 1" x 1" FR4 Board.

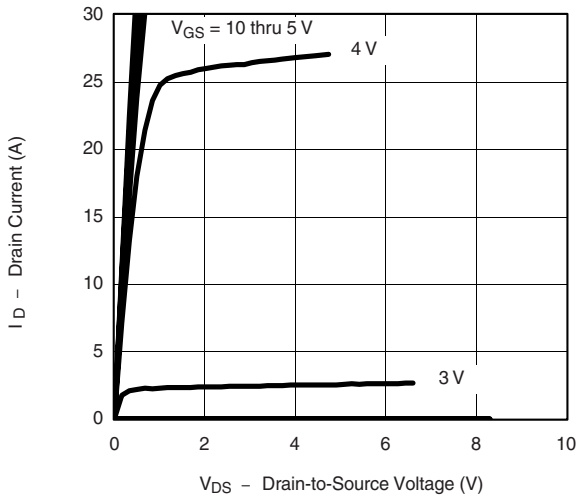
MOSFET SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min	Typ ^a	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	0.8		3.0	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\ \text{V}, V_{GS} = \pm 20\ \text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30\ \text{V}, V_{GS} = 0\ \text{V}$			1	μA
		$V_{DS} = 30\ \text{V}, V_{GS} = 0\ \text{V}, T_J = 85\text{ }^\circ\text{C}$			15	
On-State Drain Current ^b	$I_{D(on)}$	$V_{DS} = 5\ \text{V}, V_{GS} = 10\ \text{V}$	20			A
Drain-Source On-State Resistance ^b	$r_{DS(on)}$	$V_{GS} = 10\ \text{V}, I_D = 7.5\ \text{A}$		0.017	0.022	Ω
		$V_{GS} = 4.5\ \text{V}, I_D = 6.5\ \text{A}$		0.024	0.030	
Forward Transconductance ^b	g_{fs}	$V_{DS} = 15\ \text{V}, I_D = 7.5\ \text{A}$		19		S
Diode Forward Voltage ^b	V_{SD}	$I_S = 1\ \text{A}, V_{GS} = 0\ \text{V}$		0.75	1.2	V
Dynamic^a						
Total Gate Charge	Q_g	$V_{DS} = 15\ \text{V}, V_{GS} = 4.5\ \text{V}, I_D = 7.5\ \text{A}$		7	11	nC
Gate-Source Charge	Q_{gs}			2.9		
Gate-Drain Charge	Q_{gd}			2.5		
Gate Resistance	R_g		0.5	1.5	2.6	Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15\ \text{V}, R_L = 15\ \Omega$ $I_D \cong 1\ \text{A}, V_{GEN} = 10\ \text{V}, R_g = 6\ \Omega$		9	15	ns
Rise Time	t_r			10	17	
Turn-Off Delay Time	$t_{d(off)}$			19	30	
Fall Time	t_f			9	15	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 1.7\ \text{A}, di/dt = 100\ \text{A}/\mu\text{s}$	Ch-1		35	55

Notes:

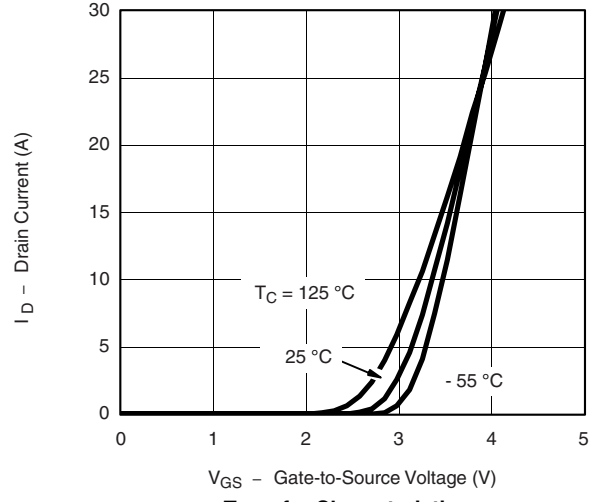
- a. Guaranteed by design, not subject to production testing.
 b. Pulse test; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

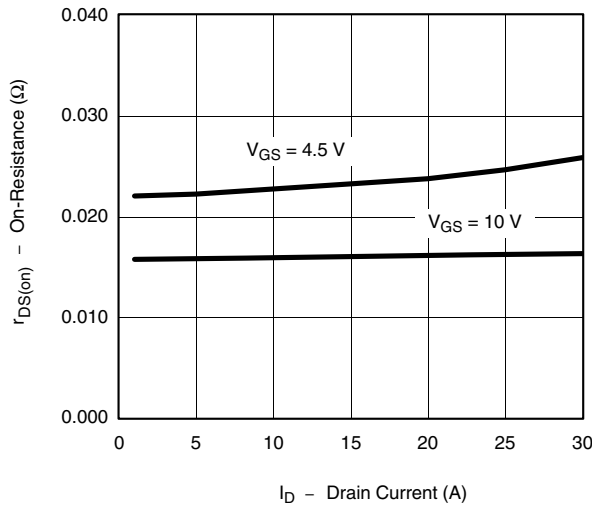
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



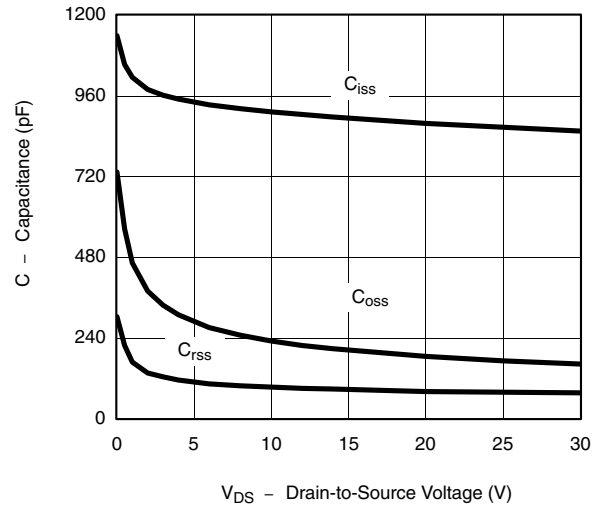
Output Characteristics



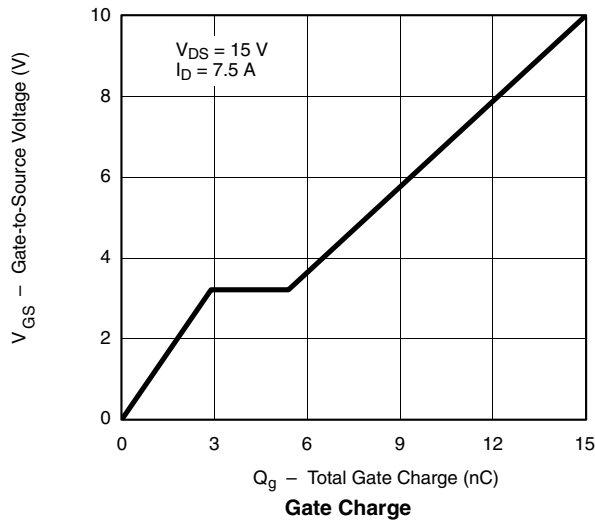
Transfer Characteristics



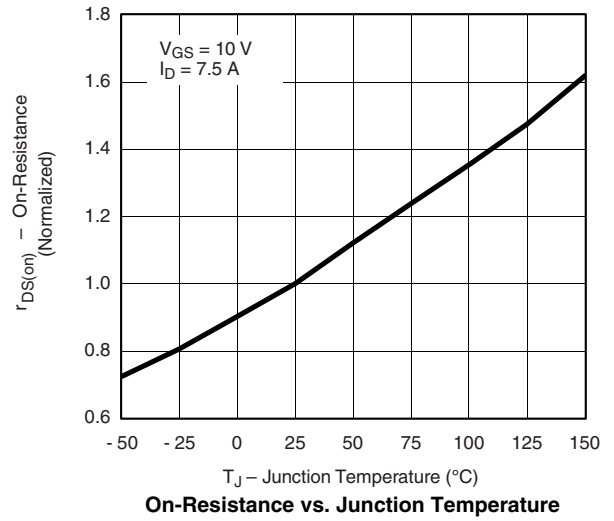
On-Resistance vs. Drain Current



Capacitance

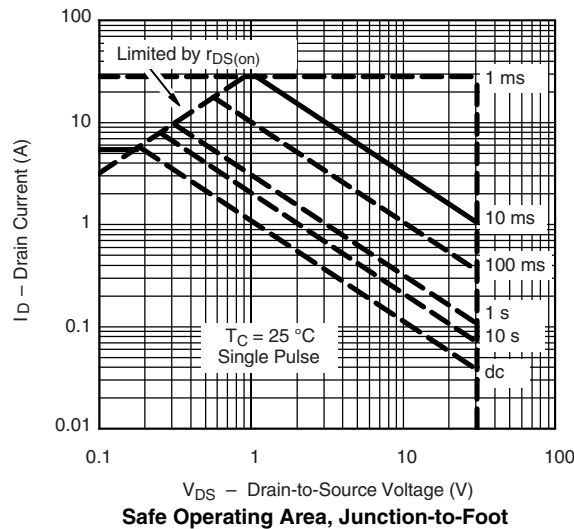
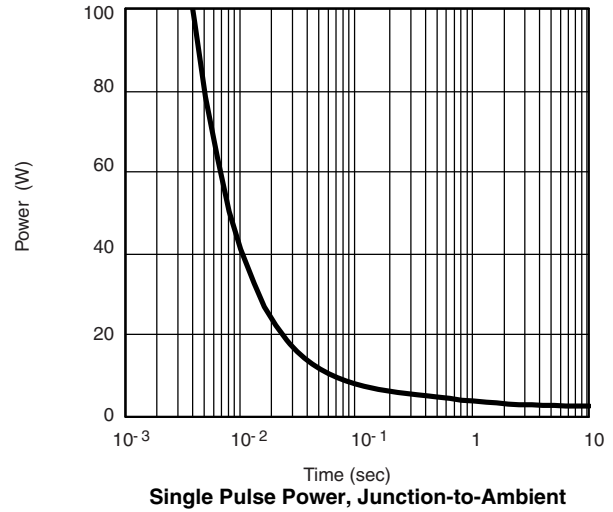
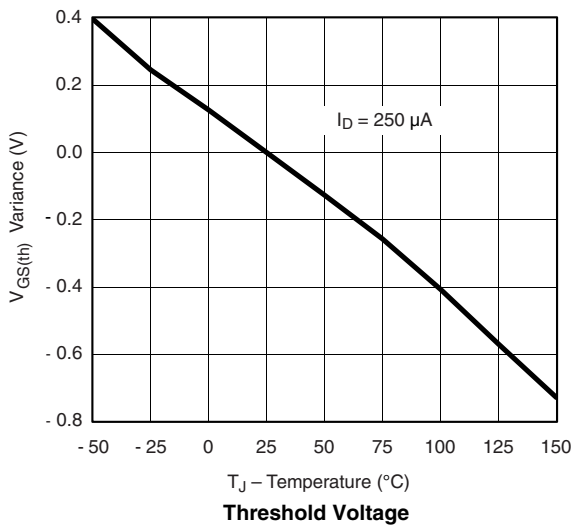
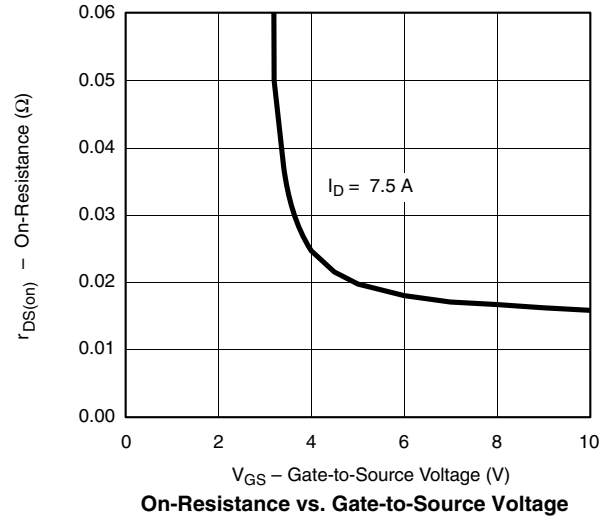
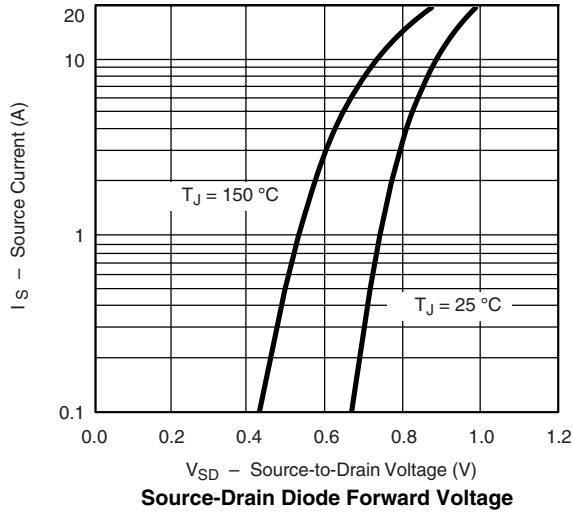


Gate Charge

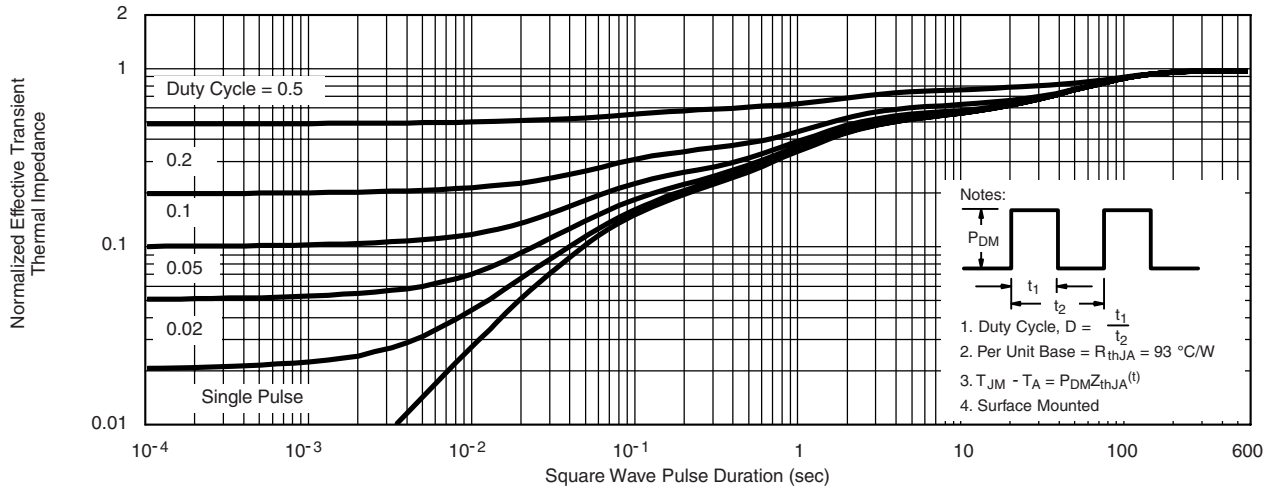


On-Resistance vs. Junction Temperature

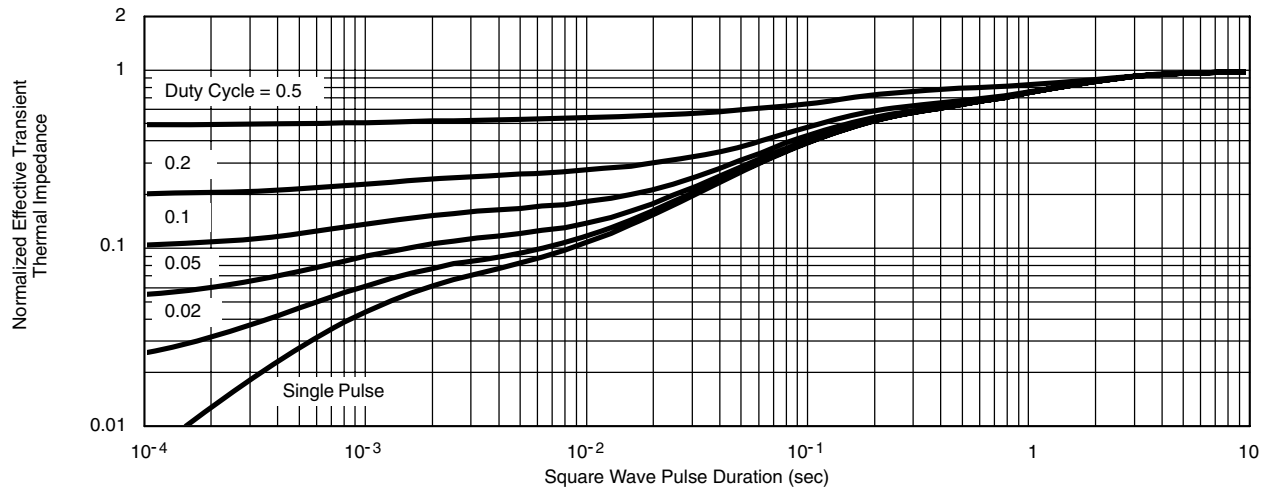
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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